

GT200

Growing Innovation



Higher throughput, increased user comfort

The GT200 is an eco-friendly manufacturing solution dedicated to wafer cleaning and stripping processes. From photoresist removal and surface activation to high-quality final cleaning, GreenTec Solutions brings complementary process capabilities together in one configurable platform. By consolidating these capabilities, the GT200 helps reduce tool fragmentation, simplify process flows, and establish a more consistent foundation for efficient and reliable production.

By combining greener process media with advanced technologies such as TurbulenStrip™ and CrustBuster™, the GT200 accelerates process learning cycles, reduces EHS exposure, and helps fabs lower chemical consumption and hazardous waste generation – without compromising process performance. Designed to address the demands of tomorrow's manufacturing environment, the GT200 eliminates the need for hazardous substances by combining greener process media with alternative stripping approaches. This enables reliable cleaning performance while consolidating multiple cleaning and stripping steps into one flexible tool concept. By reducing wafer transfers and toolset complexity, the GT200 hybrid approach supports more stable process flows, fewer interfaces, and greater operational efficiency across the production line.

99% of particles >100nm

Exclusive eco-friendly cleaning fluids

Patented in-situ UV technology

**Wafer cleaning excellence for today.
Responsibility for tomorrow.**

GT200

Highlights

Soak bath using green fluids

Optimized process timings due to multiple soak slots that can be handled individually

Ideal for stripping of thick resist layers

Oxidation of thin resist layers and organic residues using SUSS patented in-situ UV technology

Highly selectivity, little to no metal etching

Full replacement of conventional process with no hazardous or dangerous chemistry needed

Particle removal and final clean with megasonic DIW rinse and nanobinary-spray



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Technical data

General	
Dimensions (w x d x h)	237 x 420 x 230 cm
Available Modules	TurbulenStrip Crustbuster SpinRinseDry Main Handling Unit Loading / Wafer IO (Human machine interface) Media Supply Controller Electronics Media IO
Wafer Sizes	150mm up to 200 mm round substrates
Supported Wafer Materials	Si, SiC, and more
Used Media	DIW, APM, diluted H ₂ O ₂ , TS-Fluid, N ₂
Robot System	dual arm robot
Throughput	Up to 45 wafers per hour (mechanical)

Strippable Media	
Positive and Negative Tone Resists, e.g.	Novolak - DNQ based PHS based (Meth)acrylate based
Thin Organic Layers, e.g.	HMDS Deposited films
Currently not possible	Polyimides SU-8 Types

Cleanliness / PRE	
Particle Removal Efficiency	100% at 1 µm ≥ 99% at 100 nm
Cleaning Option	Resist Dissolution / Oxidization or Lift-Off Residue Removal / Descumming Particle Removal / Cleaning and Drying
Resist Removal	Soak bath for up to 15 wafer Exclusive, water-based green stripping fluid Single-wafer handling (i.e., first-in-first-out) Megasonic agitation (1 MHz) Front- and backside DI-water rinse
Residue Removal and Surface Activation	In-situ UV activated oxidization of organic residues In-situ UV based surface preparation
Particle Removal	Three arms equipped with different possibilities (Hot) DI-water rinse (front- and backside) APM rinse NanoBinary droplet spray Advanced megasonic cleaning (MegaBeam, MegPie) Pressured N ₂

Data, design and specification depend on individual process conditions and can vary according to equipment configurations. Not all specifications may be valid simultaneously. Illustrations, photos and specifications in this brochure are not legally binding. SUSS reserves the right to change machine specifications without prior notice.



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